

ABSTRACT**Method for transferring a layer from a source substrate to a destination substrate**

The present description concerns a method of transferring a layer (15) from a source substrate (13) to a destination substrate (17), comprising the following steps:

- a) arranging a masking disk on a central portion of a bonding surface of said layer (15) and/or of the destination substrate (17);
- b) implementing an ion etching to form a step (29, 30) in front of a peripheral portion, not covered with the masking disk, of the bonding surface of said layer (15) and/or of the destination substrate (17);
- c) removing the masking disk;
- d) activating the bonding surface of said layer (15) and the bonding surface of the destination substrate (17); and
- e) placing into contact the bonding surface of said layer (15) with the bonding surface of the destination substrate (17).

(Fig. 1C)